TUV-certified probing environment
- Enclosure for operator safety
- Interlock connection for test instruments
- Regulatory-approved high-voltage and high-current cables and connectors

eVue™ IV Digital Imaging System
- Fast probe set-up with wide field-of-view and single objective in MicroChamber
- Easy navigation with multiple live-video views of probes and wafer
- New high-speed focus system for faster and accurate die stepping
- New safety features for probes and usability

High-stability microscope mount
- Manual or programmable
- Gross Z lift with repeatable focus for easy access to probes

Connection panels
- Coaxial, triaxial, and pin jack feed-throughs available
- Limit cable strain and motion for measurement stability
- Instrument stays connected to back of panel
- Simple to re-arrange cabling when needed

MicroChamber®
- EMI-shielding for low-noise measurements
- Environmentally sealed for moisture-free, low-temperature measurements
- Low volume for the fastest purge
- Light-tight to eliminate the need for a dark box

TopHat™
- New TopHat covers for easier and higher-accuracy probe setup
- Allows full access to positioners and microscope at any temperature
- Allows probe adjustments without exposing wafer and chamber to external environment

AttoGuard®
- Extends instrument guard to completely surround wafer
- Makes the station invisible to the instrument
- Extremely low capacitance and leakage characteristics
- Fast settling times

PureLine™ technology
- Enhanced EM-shielding
- Ideal for low-level IV and CV measurements

Platen lift
- Easy and safe contact and separate function for probe cards and positioners
- Available micrometer adjustment to set probe card contact

MicroChamber access door
- Auto-locking door to protect wafers at cold temperatures
- Full width for easy access to wafers and cal substrates
- Hardware interlock to protect user from hazardous chuck bias voltage

Rollout stage
- Full wafer access for safe and easy loading
- Maintains chuck integrity without contaminating layers
- Easy access to calibration substrates on auxiliary chucks
- New Lift pin technology for fast manual load/unload of hot wafers

Velox™ PRO test automation software
- Easy-to-use automation for high volume data collection
- Efficient communication with test executive software
- Time-saving test recipes

Velox™ probe station control software
- Innovative operating software for advanced probe operation, temperature control, profiling and stepping
- Wafer mapping, automated wafer alignment, and auto XY2 and theta correction for sub-micron stepping

Automated wafer handling
- Up to 50 wafers with optional 2nd cassette
- Quick access port for maximum throughput
- Save time with parallel ID reading and pipelining
- Fast load/unload wafer to hot/cold chuck (55°C to +300°C)

Thin wafer testing
- Safe robot handling for thin/warped/Taiko wafers down to 50 µm
- Advanced top lift end effector for thin wafer loading with 10kV TESLA chucks

Contact Intelligence™ Technology
- Integrated HTS (High Thermal Stability) reduces probe drift and thermal soak time
- Optional VueTrack™ reduces thermal soak time (faster time to data)
- Enables unattended test over multiple temperatures

Auxiliary chucks
- High voltage (3 kV / 10 kV)
- High current (200 A)
- Low leakage
- High voltage anti-arcing probe card

Manual mode stage control
- Intuitive manual chuck XY stage controls in semi-automatic engineering mode

Precision 200 mm motorized wafer stage
- New can-selectable performance modes for standard, fast and high accuracy
- Increased test throughput with up to 100 mm/sec speed
- High reliability 24/7 operation

Patented TESLA chuck technologies
- HV FemtoGuard® (3kV / 10kV) and low leakage
- Gold-plated MicroVac™ surface for minimal chuck-to-wafer contact resistance
- 3kV, coaxial, and high current (600A) options
- Wide range of temperature options from -55°C to 300°C and higher
- Specialty chucks for >400°C, and low inductance / Capped for UIS (unclamped inductance switching)

Compact small footprint
- Integrated vibration isolation for reliable small pad probing
- Integrated system electronics with power loss wafer safety protection

Cascade

TESSLA200
200 mm On-Wafer Power Semiconductor Probing System - Fully-automatic

Up to 10 kV / 600 A with thin-wafer support (≥ 50 µm)
Accurate Rds(on) with constant Rc at all temperatures with Contact Intelligence™ Technology
Anti-arcing solutions for wafer, probes and probe cards

Contact FormFactor for more information on the TESLA200 and the complete line of TESLA probe stations.